

Please enter the following new claims:

38. A light emitting semiconductor device comprising:

an arrangement of semiconductor layers for generating light in response to a conduction of current;

an optically transparent, conductive ohmic wafer-bond layer coupled to the semiconductor layers, an interface of said wafer-bond layer with the semiconductor layers exhibiting properties characteristic of layers that have undergone wafer bonding, the wafer-bond layer directly contacting the arrangement of semiconductor layers without any intervening metallic layer contact; and

contacts for applying a current to the arrangement of semiconductor layers.

39. The device of claim 38 wherein the semiconductor layers form a light emitting diode.

40. The device of claim 38 wherein the wafer-bond layer is a transparent substrate having a thickness greater than 8 mil, the transparent substrate being wafer bonded to said semiconductor wafers.

41. The device of claim 38 further comprising a second optically transparent conductive ohmic wafer-bond layer coupled to the semiconductor layers.

REMARKS

Claims 14 through 21 are pending in this application. Claims 14 through 21 have been rejected under 35 U.S.C. § 112, second paragraph and 35 U.S.C. § 103.

Applicants are cancelling claim 18 and entering new claims 38 through 41 with this amendment.

The Examiner has objected to the term 'robust' in amended